

CH03-FA - 3FF MICRO SIM CARD CONNECTOR SMT, SLIDE IN TYPE, WITHOUT SWITCH, 6 OR 8 CONTACTS

FEATURES

1. GENERAL CHARACTERISTICS

DIMENSIONS: 13.28L x 13.7W x 2.60H mm

WEIGHT: APPROX. 0.38g

CONTACT PRINCIPLE: FRICTION TECHNOLOGY

OPERATING POSITION: SHAFT UP / DOWN / HORIZONTAL

MOUNTING SYSTEM: SMT TYPE (WITHOUT POST)

DURABILITY: 5,000 CYCLES MIN.

2. MECHANICAL CHARACTERISTICS

INSULATION MATERIAL: THERMOPLASTIC, UL 94V-0

CONTACT MATERIAL: PHOSPHOR BRONZE

CONTACT PLATING: GOLD OVER NICKEL HOLDER MATERIAL: PHOSPHOR BRONZE $\triangle 2$

ROHS DIRECTIVE 2002/95/EC COMPLIANT

3. ELECTRICAL CHARACTERISTICS

NUMBER OF CONTACTS: 6, 8 PINS (OPTIONAL)

CONTACT RESISTANCE: 50M OHMS TYP. 100M OHMS MAX.

INSULATION RESISTANCE: > 1000M OHMS / 500V DC

4. SOLDERABILITY

WAVE: NOT APPLICABLE

IR REFLOW: 260°C. 10 SEC. MAX.

MANUAL SOLDERING: 360°C, 3 SEC. MAX.

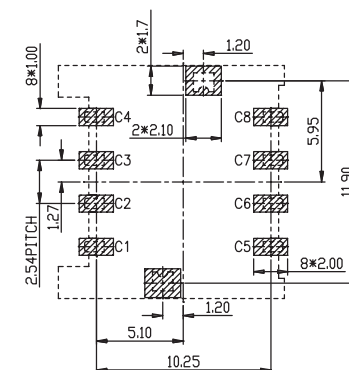
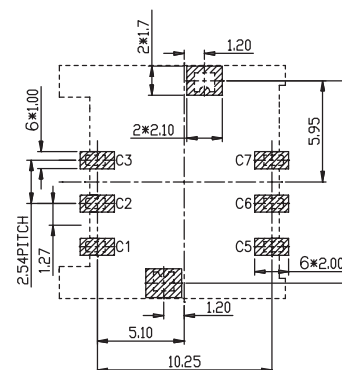
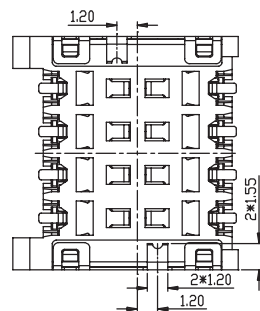
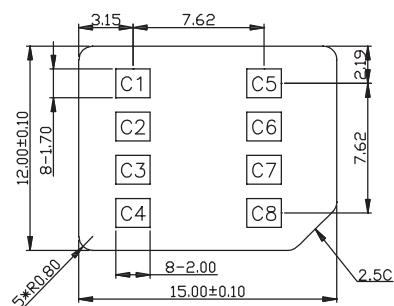
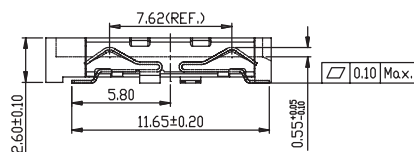
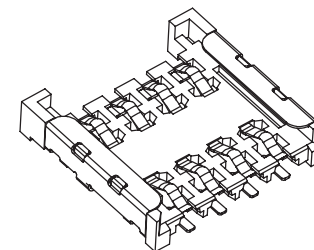
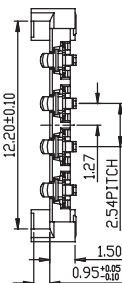
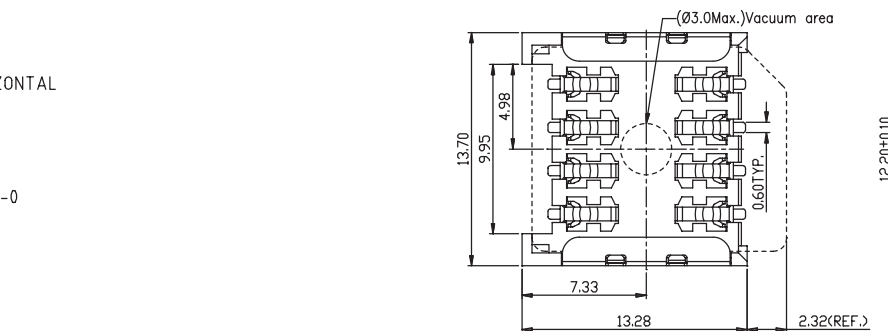
5. ENVIRONMENTAL CHARACTERISTICS

OPERATING TEMPERATURE: -40°C ~ +85°C

OPERATING HUMIDITY: 10% ~ 95% RH

STORAGE TEMPERATURE: -40°C ~ +85°C

STORAGE HUMIDITY: 10% ~ 95% RH



△₂ THICKNESS: 0.76 ±0.08
MICRO SIM CARD



(TOLERANCES: ± 0.05)
RECOMMENDED PCB LAYOUT (6 PINS)

(TOLERANCES: ± 0.05)
RECOMMENDED PCB LAYOUT (8 PINS)

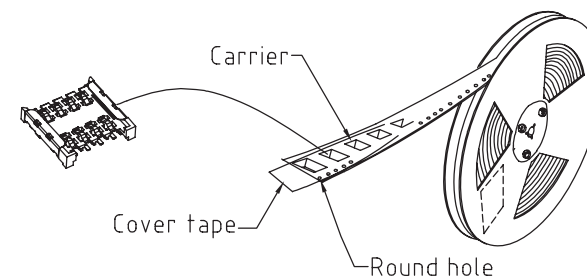
HOW TO ORDER

NO. OF CONTACTS
06 OR 08

PACKAGING OPTIONS
R = TAPE & REEL (800pcs/REEL) Δ 3

REV. DATE & DRN 11 TO 25/09/70 - NYW RELEASE 12 ADD 6MM PER LAYOUT 13 ADD PACKING DRAWINGS. 14 26/10/70 - RCE 15 ADD MATERIAL & PLATING INFO. 16 ADD SHIP CARD DRAWING. 17 28/11/70 - RCE 18 ADD SHIP CARD MULTIPLE TO 800PCS.		Scale: 3:1	THIRD ANGLE	Unstated Tolerances: .XX ± 0.15	Material SEE NOTE		Type: CH03-FA
		Drawn: NYW					
		App'd: XXXX	Title SIM CARD ACCEPTOR	NOT TO SCALE			Drawing Number:
		Date: 11 MAR '11	Revision: 1.3	Unit: mm			Sheet 1 of 2
							Drawing © E and O E

RoHS
Compliant



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